
Wire Bonding in Microelectronics

Materials, Processes,
Reliability, and Yield

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Second Edition

McGraw-Hill

New York San Francisco Washington, D.C. Auckland Bogotá
Caracas Lisbon London Madrid Mexico City Milan
Montreal New Delhi San Juan Singapore
Sydney Tokyo Toronto

Contents

Preface	xi
Acknowledgments	xiv
Chapter 1. Technical Introduction to the Second Edition	1
1.1 Wedge- and Ball-Bonding Machine Operations	2
1.2 How to Approach Bonding Problems	6
1.2.1 Which materials can be ultrasonically bonded?	6
1.2.2 Assessing the bondability and reliability of proposed new bond systems	8
1.2.3 Some unusual uses of wire bonds	10
Chapter 2. Ultrasonic Bonding Systems and Technologies (Including Ultrasonic Wire Bonding Mechanism)	11
2.1 Introduction	11
2.2 Ultrasonic Transducer and Tool Vibration Modes	11
2.3 How Ultrasonic Bonds Are Made	18
2.4 Bonding with High (er) Frequency Ultrasonic Energy	23
2.5 In-Process (Real-Time) Bond Monitoring	26
2.6 Wire-Bonding Technologies	27
2.6.1 Thermocompression bonding	27
2.6.2 Ultrasonic wedge bonding (small- and large-diameter wires)	28
2.6.3 Thermosonic Ball and Wedge Bonding	29
2.6.4 Choosing a wire-bonding technology	30
2.7 Variations of Fine Wire-Bonding Technology	30
2.7.1 Ribbon wire bonding	31
2.7.2 Parallel gap and tweezer welding	33
2.8 Major Chip Interconnection Alternatives to Wire Bonding (Flip Chip and TAB); Limits of Wire Bonding	35
2.9 Flip Chip	35
2.9.1 TAB	36
2.9.2 Wire-bonding technology: a comparison	37

Chapter 3. Some Aspects of Bonding Wire Characteristics that Can Affect Bonding, Reliability, and Testing	43
3.1 Introduction	43
3.2 Stress-Strain Characteristics of Bonding Wires	43
3.3 Shelf-Life Aging of Bonding Wires	45
3.4 General Discussion of Gold Bonding Wire	50
3.5 Aluminum Wire for Ultrasonic Wedge Bonding	52
3.6 Wire and Metallization Hardness	53
3.7 Effect of EFO Polarity on Gold Wire and Its Metallurgy	54
3.8 Metallurgical Fatigue of Bonding Wires	55
3.9 Conductor Burnout	58
3.9.1 Bonding wires	58
3.9.2 Maximum allowable current for PCB and MCM conductors	63
Appendix WM-1: A Listing of Useful ASTM Standards and Specifications on Bonding Wire and Bond Testing	63
Chapter 4. Wire Bond Testing	67
4.1 Introduction	67
4.2 The Destructive Bond Pull Test	67
4.2.1 Variables of the bond pull test	68
4.2.2 Failure predictions that are based on pull test data	70
4.2.3 Effect of metallurgy and bonding processes on the bond pull force	72
4.2.4 Effect of wire elongation on bond-pull force (large-diameter Al, and Au wire used in ball bonding)	73
4.3 Nondestructive Pull Test	78
4.3.1 Introduction	78
4.3.2 Metallurgical and statistical interpretation of NDP test	79
4.3.3 Assessment of any NDP test-induced metallurgical defects	81
4.3.4 Limitations of the NDP test	82
4.3.5 The current status of the NDPT (1996) for military and space applications	83
4.4. Ball-Bond Shear Test	84
4.4.1 Introduction	84
4.4.2 Apparatus	85
4.4.3 A manual shear probe as an aid in setting up a ball bonder	86
4.4.4 Interferences to making accurate ball-shear test measurements	89
4.4.5 Ball-shear force versus bonded area	93
4.4.6 Effect of gold-aluminum intermetallics on the shear force	97
4.4.7 Pluck test	99
4.4.8 Comparison of the ball-shear and bond-pull tests	99
4.4.9 Applications of the ball-shear test	100
4.4.10 Shear test for wedge bonds	105
4.4.11 Ball-shear test standardization	107
4.5 Evaluating Both the Ball and the Wedge Bond on a Single Wire	107
4.6 Thermal Stress Test for Al-Au Wire Bond Reliability	108
4.7 Future Issues in Wire Bond Testing	108
4.8 Appendix TA-1	110

Chapter 5. Gold-Aluminum Intermetallic Compounds and Other Metallic Interface Reactions Encountered in Wire Bonding	115
5.1 Gold-Aluminum Intermetallic Compound Formation and Classical Wire Bond Failures	115
5.1.1 Introduction	115
5.1.2 Intermetallic compound formation	116
5.1.3 The classical Au-Al compound failure modes	122
5.1.4 Reversing metallurgical interfaces	127
5.1.5 The effect of diffusion inhibitors and barriers	128
5.2 Impurity-Accelerated Au-Al Bond Failures	129
5.2.1 The effect of halogens on the Au-Al bond system	130
5.2.2 Recommendations for removing or avoiding halogen contamination	134
5.2.3 Nonhalogen epoxy outgassing induced bond failures	135
5.3 Non-gold-aluminum Bond Interfaces	135
5.3.1 Aluminum-copper wire bond system	135
5.3.2 Aluminum metallization containing copper	137
5.3.3 Copper-gold wire bond system	138
5.3.4 <i>Palladium-Au and -Al bonding system (used for lead frames)</i>	140
5.3.5 The silver-aluminum wire bond system	142
5.3.6 Aluminum-nickel wire bond system	144
5.3.7 Au-Au, Al-Al, Au-Ag, and less-used monometallic bonding systems	145
Appendix IA-1: Rapid Bond Failure in Poorly Welded Au-Al Bonds	149
Appendix IA-2: Various Bond-Related Corrosion Reactions	152
Chapter 6. Bond Failures Resulting from Gold-Plating Impurities and Conditions	161
6.1 Introduction	161
6.2 Specific Plating Impurities	163
6.3 Hydrogen Gas in Plated Films	165
6.3.1 Hydrogen-induced package problems	170
6.3.2 Failure symptoms that appear similar to gas entrapments: resistance drift	170
6.4 Failures from Metallic Impurities in or on Gold Films That Are Not an Intentional Part of Plating Baths	171
6.4.1 Introduction	171
6.4.2 Nickel	173
6.4.3 Copper	174
6.4.4 Chromium	175
6.4.5 Titanium	175
6.4.6 Tin	176
6.5 Gold-Plating Standards	176
6.5.1 Recommendations for reliable gold-plated films	176
6.6 Electroless Autocatalytic Gold	177
6.7 Nongold Platings Used in Electronics Packaging	178
Chapter 7. Cleaning to Improve Bondability and Reliability	181
7.1 Introduction	181
7.1.1 Molecular cleaning methods to enhance bondability and reliability	184

7.1.2	Ultraviolet-ozone cleaning	185
7.1.3	Plasma cleaning	187
7.1.4	Plasma cleaning mechanism	190
7.1.5	Discussion and evaluation of molecular and solvent cleaning methods	192
7.1.6	Problems encountered in using molecular cleaning methods	193
7.1.7	Burnishing	195
7.2	The Sensitivity of Different Bonding Technologies to Surface Contamination	196
	Appendix CL-1: Circuit Damage Caused by Plasma Cleaning during Packaging	198
Chapter 8. Mechanical Problems in Wire Bonding		203
8.1	Cratering	203
8.1.1	Introduction	203
8.1.2	Bonding machine characteristics and setup parameters	207
8.1.3	Bonding force	208
8.1.4	Tool wire-pad impact force	209
8.1.5	Causes of cratering—materials	210
8.1.6	Intermetallics	213
8.1.7	Silicon nodule-induced cratering	215
8.1.8	Cratering over polysilicon	217
8.1.9	Gallium arsenide cratering	219
8.2	Cracks in the Heels of Ultrasonic Wedge Bonds	223
8.3	The Effect of Acceleration, Vibrations, and Shock	226
8.3.1	Centrifuge effects on wire bonds	226
8.3.2	The effect of ultrasonic cleaning on wire bonds	228
8.3.3	The effect of shock and vibration tests on wire bonds	231
8.4	Effects of Power and Temperature Cycling of Wire Bonds	231
	Appendix M-1: Fracture Toughness Defined	236
Chapter 9. High-Yield and Fine-Pitch Wire Bonding		241
9.1	Introduction	241
9.2	The Background Necessary to Achieve High-Yield Bonding	242
9.3	The Requirements for High-Yield Bonding	243
9.3.1	Clean, bondable metallization	243
9.3.2	The bonding machine and its control	247
9.4	Reliability for Small Numbers of Bonds (Small Sample Statistics)	248
9.5	Package-Related Bond-Yield Issues	250
9.6	Possible 6σ Yield Enhancements and Problems that Need Further Study	251
9.7	Other Conclusions that May Affect Device Yield	253
9.7.1	Wire sweep	253
9.7.2	Wire looping	254
9.8	Fine-Pitch Ball and Wedge Bonding	255
9.8.1	Introduction	255
9.8.2	Fine-pitch ball and wedge bonding	255
9.9	The Problems of Fine-Pitch Bonding	257
9.10	Conclusions	259
9.11	Acknowledgments	260

Chapter 10. Wire Bonding to Multichip Modules and Other Soft Substrates	263
10.1 Introduction	263
10.2 Bonding to MCM-D Substrates	264
10.3 Bonding to MCM-L Substrates	266
10.4 The Effect of the Substrate's Material Properties on Wire Bonding	269
10.5 Bonding Machine Considerations	274
10.6 Additional Considerations When Using Wire Bonds in MCMs	
Running at High Clock Rates	275
10.6.1 Inductance of wire bonds	275
10.6.2 Skin-effect in typical MCM conductor metal structures	276
10.7 Conclusions	278
10.8 Acknowledgments	278
Glossary	281
Index	285